Product Specification

Product:	Tungsten Paste
Part Number:	32H-1801P

Application Scope :
This product is suitable for ceramic circuit printing.

The main features are as follows:
- ❖ The shrinkage rate is consistent with that of ceramic, and the bonding strength between sintering and ceramic is good.
- ❖ The resistance value is small.
- ❖ It can meet the requirements of printing and perforation filling.
- ❖ The metal particles are well dispersed and the metallized surface should be flat.
- ❖ Suitable for 95-96% alumina ceramics, especially suitable for metallization of dense ceramics.

This Nickel paste apply to alumina ceramic conductive paste，MLCC, etc.

Usage Conditions :

Substrate	Alumina ceramic
Printing	200-250 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (depending on the actual leveling time).
Drying	Bake in an oven at 100-150°C for 10-15 minutes (temperature below 230°C)
Firing Condition	Sintering in a tunnel furnace under a hydrogen protective atmosphere, with a peak of 1350~1700°C (recommended value) and a peak of 30-45 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤5μm	FOG test
2	Viscosity	180-420Pa.s	Brookfield HBT viscometer (Rotor SC4-14/6R), 10 rpm, 25±1°C

2. Characteristics After Curing :

Under sintering conditions, the film thickness ranges from 8 to 12 microns.

Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

Characteristics		Standard	Test Method And Conditions
3	Resistivity	≤20mΩ/□	Test pattern 0.6mm×60mm

Save Conditions And Validity Period :

The product should be stored in a sealed environment at 5-25°C. The shelf life is 1 year from the date of shipment.

Packaging Method :

Standard packaging: 1000g per can. Samples are available in 200g small cans.